

# USER MANUAL

## Maxwell Technologies, Inc. Soldering Guide: Small and Medium Ultracapacitor Cells

### Models:

- 2.7V 3F – 2.7V 360F
- Pseudo 2.3V 50F – 2.3V 300F



**Maxwell Technologies, Inc.**  
**Global Headquarters**  
3888 Calle Fortunada  
San Diego, CA 92123  
USA  
Phone: +1 (858) 503-3300  
Fax: +1 (858) 503-3301



**Maxwell Technologies SA**  
Route de Montena 65  
CH-1728 Rossens  
Switzerland  
Phone: +41 (0)26 411 85 00  
Fax: +41 (0)26 411 85 05



**Maxwell Technologies GmbH**  
Leopoldstrasse 244  
80807 München  
Germany  
Phone: +49 (0)89 4161403 0  
Fax: +49 (0)89 4161403 99



**Nesscap Co., Ltd**  
17, Dongtangiheung-ro  
681 Beon-gil, Giheung-gu,  
Yongin-si, Gyeonggi-do 17102  
Republic of Korea  
Phone: + +82 31 289 0721  
Fax: +82 31 286 6767



**Maxwell Technologies  
(Shanghai) Trading Co., Ltd**  
Room 1005, 1006 and 1007  
No. 1898, Gonghexin Road,  
Jing An District, Shanghai 200072  
P.R. China  
Phone: +86 21 3680 4600  
Fax: +86 21 3680 4699



**Maxwell Technologies  
Shanghai Representative Office**  
Rm 1008  
No. 1898, Gonghexin Road,  
Jing An District, Shanghai 200072  
P.R. China  
Phone: +86 21 3680 4600  
Fax: +86 21 3680 4699

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## 1. Introduction

### 1.1 Purpose and Scope

The purpose of this document is to provide a general guideline on soldering Maxwell small and medium size ultracapacitors onto PCBs. The soldering parameters presented in this document are guidelines for process optimization. Actual results of soldering may vary with types of solder material and equipment used.

### 1.2 Applicable Products

Maxwell small and medium size cells to which this document is applicable are shown in Table 1.

Product Rating	Model Number
Standard 2.7V-3F	BCAP0003 P270 S01
Bent 2.7V-3F	BCAP0003 P270 S12
XP 2.7V-3F	BCAP0003 P270 X01
Standard 2.7V-5F	BCAP0005 P270 S01
XP 2.7V-5F	BCAP0005 P270 X01
Standard 2.7V-10F	BCAP0010 P270 S01
Bent 2.7V-10F	BCAP0010 P270 S12
XP 2.7V-10F	BCAP0010 P270 X01
Standard 2.7V-25F	BCAP0025 P270 S01
Bent 2.7V-25F	BCAP0025 P270 S12
XP 2.7V-25F	BCAP0025 P270 X01
Standard 2.7V-50F	BCAP0050 P270 S01
XP 2.7V 50F	BCAP0050 P270 X01
2.7V 100F	BCAP0100 P270 S07
2.7V 325F	BCAP0325 P270 S17
2.7V 360F	BCAP0360 P270 S18
Pseudo 2.3V-50F	PCAP0050 P230 S01
Pseudo 2.3V-120F	PCAP0120 P230 S01
Pseudo 2.3V-300F	PCAP0300 P230 S07

**Table 1:** Maxwell products that are subjected to soldering recommendations listed in this document

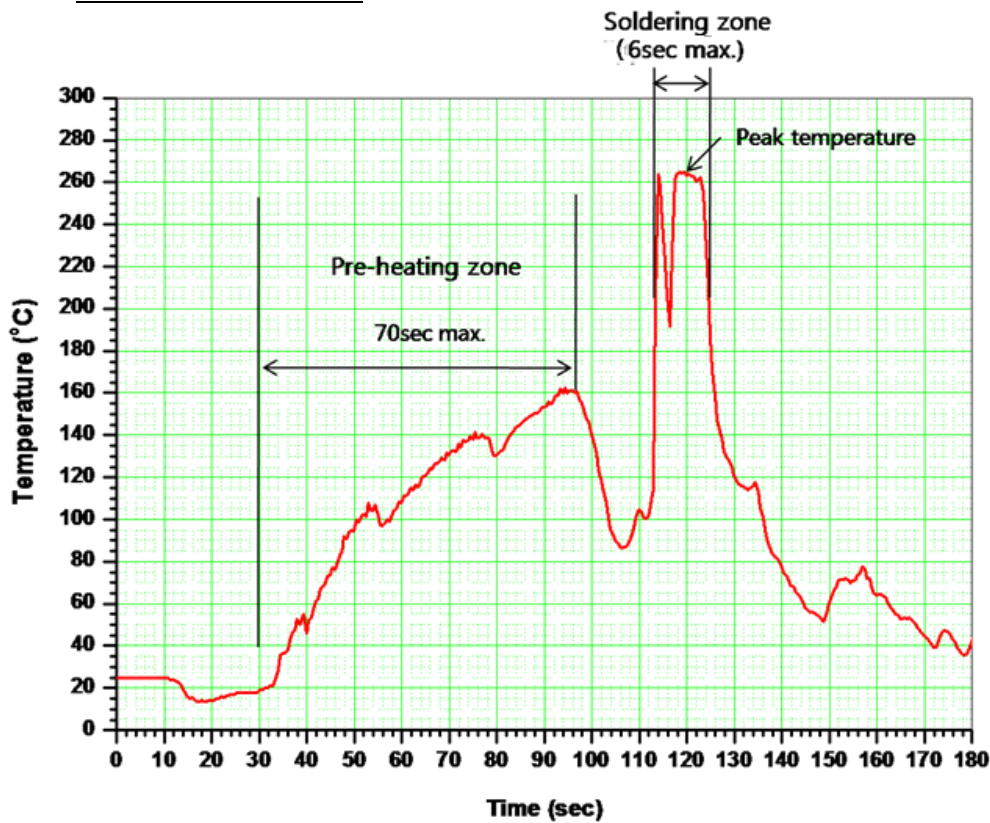
## 2. Manual Soldering Recommendations

For manual soldering of Maxwell small and medium ultracapacitors, the recommended maximum solder tip temperature is  $\sim 360^{\circ}\text{C}$ . Soldering time for each terminal must be kept under 5 seconds to minimize exposing the cell to high temperatures.

## 3. Wave Soldering Recommendations

### 3.1 Reference Temperature Profile

Figure 1 in the next page is the reference temperature profile measured from the bottom of a PCB.



**Figure 1:** Reference temperature profile for wave soldering (measured from the bottom of PCB)

### 3.2 Preparation

Use of excessive soldering flux should be avoided to minimize possibility of the cell terminal corrosion. Cells should be placed in a way that the crimp area of every cell is flush with the PCB surface.

### 3.3 Pre-heating Zone

The set temperature of the equipment in the pre-heating zone is approximately 250°C. Since the ambient temperature is 250°C and the time spent in the pre-heating zone is less than 70 seconds, the actual temperature of the PCB shown in the profile is lower than 250°C. The rate of PCBA movement, through the pre-heating zone, is set at 1m/min for all small and medium cells, except for 325F cell. In case of the 325F product, the recommended speed of PCBA movement is 0.8m/min.

### 3.4 Soldering Zone

A soldering temperature of approximately 260°C is recommended for all small and medium cells. In the reference temperature profile shown in Figure 1. above, the terminals of the cell go through two "solder sessions" and the total time spent in immersion (the sum of the two solder sessions) should not exceed 6 seconds. Depending on the equipment used and the user's preference, only one solder session may be used. The rate of PCBA movement, through the soldering zone, is same as the pre-heating zone: 1m/min for all small and medium cells except the 325F cell and 0.8m/min for the 325F cell.

### 3.5 Post-Solder Cleaning

Maxwell recommends the use of no-clean type flux. If clean type flux is to be used, isopropyl alcohol is recommended as the cleaning agent; which is applied to soldered areas using a brush. Immersion cleaning in organic solvents or ultrasonic cleaning is prohibited as it may have a detrimental impact on ultracapacitor performance. Additionally, the use of halogenated cleaners is prohibited. Table 2 lists some examples of halogenated substances that **must not** be used as cleaning agents.

Name	Chemical Formula	Product Name
Trichlorotrifluoroethane	C <sub>2</sub> Cl <sub>3</sub> F <sub>3</sub>	Freon TF, Dailflon S-3
Fluorotrichloromethane	CCl <sub>3</sub> F	Freon-11, Daiflon S-1

1,1,1-Trichloroethane	F <sub>2</sub> H <sub>3</sub> Cl <sub>3</sub>	Chloethane
Trichloroethylene	C <sub>2</sub> HCl <sub>3</sub>	Trichene
Methyl Chloride	CH <sub>3</sub> Cl	MC

**Table 2:** Halogenated cleaners **prohibited** from use in post-solder cleaning

## 4. Additional Information

### 4.1 Handling of PCBA

Once the cells are soldered on a PCB, the following precautions must be taken when handling the finished PCBA.

- 1) PCBAs must be held by the board and not by the cell(s) as it may place undue mechanical stress on the cell(s) and result in permanent damage to the cell structure.
- 2) The **PCBA must not be placed or handled** vertically as it may stress the cell(s) and result in separator damage and/or electrolyte leakage of the cell(s).
- 3) The board **must not be bent** by any external force as it may cause formation of cracks within the PCB components and/or post-solder defects
- 4) After assembly, place PCBAs in anti-static bags to prevent ESD damage
- 5) The PCBAs **must not be stacked** on top of one another during storage or transportation

### 4.2 Reflow Soldering

Reflow soldering is prohibited due to extreme thermal exposure which may be experienced by the cell(s) in the soldering process.

### 4.3 Repetitive Soldering

In case the cell terminal is not soldered properly onto a PCB, both the PCB and the cell should be cooled down before attempting a second solder. If there is not enough cooling time allocated, it may lead to leakage issues following the second solder.

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